

SEMICONDUCTOR DEVICE HAVING SELF-ALIGNED CONTACT
AND FABRICATING METHOD THEREFOR

SN#09231385

Abstract of the Disclosure

A semiconductor device having a self-aligned contact and a method for
5 fabricating the same are provided. The semiconductor device includes a plurality of
conductive patterns formed to be adjacent to one another by sequentially stacking and
patterning a first conductive layer and a mask layer on a particular underlying layer. A
first insulation layer fills a gap between adjacent conductive layer patterns such that the
upper portion of each conductive layer pattern is exposed. A second insulation layer
10 having a spacer shape is formed on the sides of each conductive layer pattern exposed
above the first insulation layer. A second conductive layer fills a contact hole which is
self-aligned with respect to the second insulation layers between adjacent conductive
layer patterns and passes through the first insulation layer.

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